

Amendment under 37 C.F.R. § 1.111  
Application No. 10/721,384

**AMENDMENTS TO THE SPECIFICATION**

**Please replace the present title with the following title:**

~~HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE AND METHOD OF  
MANUFACTURING THE PACKAGE~~ HIGH PERFORMANCE CHIP SCALE LEADFRAME  
WITH T SHAPE DIE PAD AND METHOD OF MANUFACTURING PACKAGE